



# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Mahalingam Nandakumar, et al. Art Unit: 2811

Serial No.: 09/876,292

Examiner: TBD

Filed: 06/07/01

Docket: TI-31089

For: Additional n-Type LDD/Pocket Implant for Improving Short-Channel NMOS ESD

Robustness

#4

## LETTER TO THE OFFICIAL DRAFTSPERSON

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**  
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on 8-20-01 as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents Application Processing Division's Customer Correction Branch, Washington, D.C. 20231.

Karen Vertz  
Karen Vertz

8-20-01  
Date

Assistant Commissioner for  
Patents  
Washington, D. C. 20231

Dear Sir:

Enclosed are **FOUR (4)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Respectfully submitted,

*Gary C. Honeycutt*  
Gary C. Honeycutt  
Reg. No. 20,250  
Attorney for Applicants

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